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SEARCH REPORT

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STIC Database Tracking Number: 302513

To: JOSE DEES	From: DIANE JACKSON
Location: JEF-8D59	Location: EIC2800
Art Unit: 2800	JEF-4B68
Monday, July 20, 2009	Phone: (571)272-3260
Case Serial Number: 10/761098	diane.jackson@uspto.gov

Search Notes

Attached are litigation search results in Lexis Nexis, and CourtLink and Questel-Orbit.

No Litigation was found for Serial Number 10/761098.

If you have any questions, please feel free to contact me.

Thanks,

Diane

Jackson, Diane JUL 20 2009 3 02513

From: Dees, Jose
Sent: Monday, July 20, 2009 11:52 AM
To: STIC-EIC2800
Subject: Reissue 10/761098

Please do a litigation search for these related patents. 6,081,029 and 6,455,348. Thanks.

Jose' G. Dees
Jose' G. Dees
T-QAS, TC 2800
571-272-1569

Selected file: PLUSPAT

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Last update of file: 2009/07/17 (YYYY/MM/DD) 2009-29/UP (last update)

Search statement 1

nbr /pn us6081029

PLUSPAT1	US6081025	1
PLUSPAT2	US6081026	1
PLUSPAT3	US6081027	1
PLUSPAT4	US6081028	1
PLUSPAT5	US6081029	1
PLUSPAT6	US608103	1
PLUSPAT7	US6081030	1
PLUSPAT8	US6081031	1
PLUSPAT9	US6081032	1
PLUSPAT10	US6081033	1
PLUSPAT11	US6081034	1
PLUSPAT12	US6081035	1
PLUSPAT13	US6081036	1
PLUSPAT14	US6081037	1
PLUSPAT15	US6081038	1

Some: numbers / Continue: Y / None: N

Search 1 - 5 - 1
** SS 1: Results 1

Continue: Y / N

Search 1 - prt full legalall max - 1
** SS 1: Results 1

Select All | Unselect All

☐ 1 / 1 PLUSPAT - Worldwide Patents - ©Questel

US6081029 (A) Resin encapsulated semiconductor device having a reduced thickness and im...
PN US6081029 A 20000627 [US6081029]
TI (A) Resin encapsulated semiconductor device having a reduced thickness and improved reliability
PA (A) MATSUSHITA ELECTRONICS CORP (JP)

PA0 Matsushita Electronics Corporation, Osaka [JP]
IN (A) YAMAGUCHI YUKIO (JP)
AP US24407499 19990204 [1999US-0244074]
PR JP6081198 19980312 [1998JP-0060811]
IC (A) H01L-023/28 H01L-023/36 H01L-023/495 H01L-023/50
ICAA H01L-023/50 [2006-01 A F I R M JP]
H01L-021/56 [2006-01 A - I R M EP]
H01L-023/12 [2006-01 A L I R M JP]
H01L-023/28 [2006-01 A L I R M JP]
H01L-023/31 [2006-01 A - I R M EP]
H01L-023/495 [2006-01 A - I R M EP]
ICCA H01L-021/02 [2006 C - I R M EP]
H01L-023/12 [2006 C L I R M JP]
H01L-023/28 [2006 C - I R M EP]
H01L-023/48 [2006 C - I R M EP]
EC H01L-021/56B
H01L-023/31H2
H01L-023/495G2
H01L-023/495G4
H01L-023/495G4B
PCL ORIGINAL (O) : 257718000; CROSS-REFERENCE (X) : 257E23045 257E23046 257E23047 257E23125 257666000 257675000 257684000 257692000 257696000 257698000 257797000
DT Basic
Unspecified source
CT US5105259 [US5105259] 257667000
US5157480 [US5157480] 361424000
US5172214 [US5172214] 257676000
US5225897 [US5225897] 257787000
US5381042 [US5381042] 257712000
US5521429 [US5521429] 257676000
US5641987 [US5641987] 257675000
US5652461 [US5652461] 257675000
US5731632 [US5731632] 257717000
US5835988 [US5835988] 257684000
US5872395 [US5872395] 257675000
US5900676 [US5900676] 257787000
STG (A) Patent
AB A lead frame including signal-connecting leads, a die pad and support leads is provided. A semiconductor chip is bonded to the die pad with an adhesive. The semiconductor chip, electrode pads and the signal-connecting leads are electrically connected to each other with metal fine wires. And these members are encapsulated in a resin encapsulant. The back surface of the die pad is subjected to half etching or the like to form a convex portion and a flange portion surrounding the convex portion. Since a thin layer of the resin encapsulant exists under the flange portion, the resin encapsulant can hold the die pad more strongly and the moisture resistance of the device can be improved with the lower surface of the die pad protruding from the resin encapsulant. As a result, the characteristics of a resin-molded semiconductor device having a die pad exposed on the back surface of a resin encapsulant can be improved.
UP 2000-26

1 / 1 LGST - Legal Status -
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US6081029 19990204 US/ASA [NMC]ASSIGNMENTOWNER: MATSUSHITA ELECTRONICS CORPORATION, J...

PN US6081029 A 20000627 [US6081029](A) Patent

AP US24407499 19990204 [1999US-0244074]
19990204 US-API [POS; EXM]
FILING DETAILS

PUB US24407499 19990204 [1999US-0244074]
20000627 US-A [POS; EXM]
Patent
US6081029 A 20000627 [US6081029]
19990204 US/AS-A [NMC]
ASSIGNMENT
OWNER: MATSUSHITA ELECTRONICS CORPORATION, JAPAN; EFFECTIVE DATE: 19990129
ASSIGNMENT OF ASSIGNORS INTEREST;ASSIGNOR:YAMAGUCHI, YUKIO;REEL/FRAME:009753/0250

20020129 US/AS-A [NMC]
ASSIGNMENT
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION /AR;REEL/FRAME:012495/0898

ACT
20020129 US/AS-A [NMC]
ASSIGNMENT
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

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OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., JAPAN; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

LEG NMC
Alive

UP 2009-18

1 / 1 CRXX - US Claims Reassignations -
©CLAIMS/RRX

US6081029 20020129 REASSIGNEDCHANGE OF NAMEAssignor: MATSUSHITA ELECTRONICS CORPORATIO...
AN 3343780
PN 6,081,029 A 20000627 [US6081029]
PA Matsushita Electronics Corp JP
PT E (Electrical)
20020129 REASSIGNED
CHANGE OF NAME

Assignor: MATSUSHITA ELECTRONICS CORPORATION DATE SIGNED: 04/04/2001

Assignee: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMA
ACT KADOMA CITY, OSAKA JAPAN

Reel 012495/Frame 0898

Contact: SUGHRUE MION, PLLC DAVID J. CUSHING 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, D.C. 20037-3213

UP 2002-28
URAS 2002-07-09

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Search statement   2
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Selected file: FAMPAT

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Last update of file: 2009/07/17 (YYYY/MM/DD) 2009-29/UP (last update)

Search statement   1
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nbr /pn us6081029

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FAMPAT2	US6081026	1
FAMPAT3	US6081027	1
FAMPAT4	US6081028	1
FAMPAT5	US6081029	1
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FAMPAT7	US6081030	1
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FAMPAT12 US6081035 1
FAMPAT13 US6081036 1
FAMPAT14 US6081037 1
FAMPAT15 US6081038 1
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** SS 1: Results 1

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Search 1 - prt full legalall max - 1
** SS 1: Results 1

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JP11260985 Resin encapsulated semiconductor device having a reduced thickness and improv...

FAN 20090100129788
JP11260985 A 19990924 [JP11260985]
PN US6081029 A 20000627 [US6081029]
JP3285815 B2 20020527 [JP3285815]
TI Resin encapsulated semiconductor device having a reduced thickness and improved reliability
PA MATSUSHITA ELECTRONICS CORP
PA0 Matsushita Electronics Corporation, Osaka [JP]
IN YAMAGUCHI YUKIO
AP 1998JP-0060811 19980312
1999US-0244074 19990204
PR 1998JP-0060811 19980312
IC H01L-021/02
H01L-021/56
H01L-023/12
H01L-023/28
H01L-023/31
H01L-023/36
H01L-023/48
H01L-023/495
H01L-023/50
ICAA H01L-023/50 [2006-01 A F I R M JP]
H01L-021/56 [2006-01 A - I R M EP]
H01L-023/12 [2006-01 A L I R M JP]
H01L-023/28 [2006-01 A L I R M JP]
H01L-023/31 [2006-01 A - I R M EP]
H01L-023/495 [2006-01 A - I R M EP]
ICCA H01L-021/02 [2006 C - I R M EP]

H01L-023/12 [2006 C L I R M JP]
H01L-023/28 [2006 C - I R M EP]
H01L-023/48 [2006 C - I R M EP]
H01L-021/56B
H01L-023/31H2

EC H01L-023/495G2
H01L-023/495G4
H01L-023/495G4B

PCL ORIGINAL (O) : 257718000; CROSS-REFERENCE (X) : 257E23045 257E23046 257E23047 257E23125 257666000 257675000 257684000 257692000 257696000 257698000 257797000

FI H01L23/50 F; H01L23/50 G; H01L23/50 R; H01L23/50 U; H01L23/28 A; H01L23/12 501T

FTM 4M109 AA01; 4M109 BA01; 4M109 CA01; 4M109 CA21; 4M109 DA01; 4M109 DB02; 4M109 DB15; 4M109 DB17; 4M109 ED03; 5F067 AA03; 5F067 AA04; 5F067 BD05; 5F067 BD10; 5F067 BE01; 5F067 BE04; 5F067 CA04; 5F067 DC16; 5F067 DC17; 5F067 DE01; 5F067 DF16; 5F067 DF17; 5F067 EA02; 5F067 EA04

(US6081029)
Unspecified source

CT US5105259 [US5105259] 257667000
US5157480 [US5157480] 361424000
US5172214 [US5172214] 257676000
US5225897 [US5225897] 257787000
US5381042 [US5381042] 257712000
US5521429 [US5521429] 257676000
US5641987 [US5641987] 257675000
US5652461 [US5652461] 257675000
US5731632 [US5731632] 257717000
US5835988 [US5835988] 257684000
US5872395 [US5872395] 257675000
US5900676 [US5900676] 257787000

(JP11260985)
(A) Examiner citations - reason for refusal [19]

CT JP (A) 1988169753 [JP63169753]
JP (A) 1987254457 [JP62254457]
JP (A) 1992196574 [JP04196574]
JP (A) 1995297344 [JP07297344]
JP (A) 1992003450 [JP04003450]
JP (A) 1991214763 [JP03214763]

(US6081029)

AB A lead frame including signal-connecting leads, a die pad and support leads is provided. A semiconductor chip is bonded to the die pad with an adhesive. The semiconductor chip, electrode pads and the signal-connecting leads are electrically connected to each other with metal fine wires. And these members are encapsulated in a resin encapsulant. The back surface of the die pad is subjected to half etching or the like to form a convex portion and a flange portion surrounding the convex portion. Since a thin layer of the resin encapsulant exists under the flange portion, the resin encapsulant can hold the die pad more strongly and the moisture resistance of the device can be improved with the lower surface of the die pad protruding from the resin encapsulant. As a result, the characteristics of a resin-molded semiconductor device having a die pad exposed on the back surface of a resin encapsulant can be improved.

OBJ

encapsulant, a method for manufacturing such a device, and a lead frame suitable for manufacturing the resin-molded semiconductor device.
In particular, the present invention relates to an improved device with a reduced thickness.
A first object of this invention is providing a resin-molded semiconductor device suppressing delamination of a die pad by making a resin encapsulant hold the pad more strongly when the lower surface of the pad is exposed on the encapsulant, and a lead frame suitable for manufacturing such a device.
A second object is providing a resin-molded semiconductor device, preventing a resin encapsulant from cracking due to penetration of water or moisture between a die pad and the encapsulant, and a lead frame suitable for manufacturing such a device.
A third object is providing a resin-molded semiconductor device that can be self-aligned with a desired position on a motherboard more accurately by using a structure where the lower surface of a die pad is exposed on the resin encapsulant, and a method for manufacturing the same.
A fourth object is providing a resin-molded semiconductor device with heat radiation characteristics improved by preventing the formation of resin burr even if the lower surface of a die pad is exposed on the encapsulant, a manufacturing method thereof, and a lead frame suitable for manufacturing such a device.
A fifth object is providing a resin-molded semiconductor device in which solder balls need not be interposed between a die pad and a heat-radiating pad, and a method for manufacturing the same.
A first lead frame according to the present invention includes:
an outer frame surrounding a region in which a semiconductor chip is mounted; a die pad formed in the region surrounded by the outer frame; a support portion for supporting the die pad by connecting the die pad to the outer frame; and signal-connecting leads connected to the outer frame.
(US6081029)
Thus, if encapsulation is performed with a seal tape adhered to the lower surface of the lead frame, then the die pad is advantageously forced into the seal tape.
In addition, since penetration of water or moisture through the back surface of the resin-molded semiconductor device can also be advantageously suppressed as described above, the second object is achieved as well.
A second resin-molded semiconductor device according to the present invention includes:
a semiconductor chip having electrode pads; a die pad for supporting the semiconductor chip
ADB thereon; signal-connecting leads; connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members.
This is because the die pad cannot be in satisfactory contact with a heat-radiating pad in such a case.
However, such a process is not just troublesome, but causes additional problems.
Specifically, if a water jet process is carried out, then a nickel, palladium or gold plated layer might peel off and impurity might deposit on the exposed parts.
(US6081029)
1. A lead frame comprising:
an outer frame surrounding a region in which a semiconductor chip is mounted;
a die pad formed in the region surrounded by the outer frame;
support leads for supporting the die pad by connecting the die pad to the outer frame; and
ICLM signal-connecting leads connected to the outer frame,
wherein the die pad is located below the outer frame, and part of each said support lead is bent to function as a spring.
2. A lead frame comprising:
an outer frame surrounding a region in which a semiconductor chip is mounted;
a die pad formed in the region surrounded by the outer frame;

support leads for supporting the die pad by connecting the die pad to the outer frame; and signal-connecting leads connected to the outer frame,
wherein the die pad is located below the outer frame, the support leads are provided between the signal-connecting leads and the die pad, and part of each said support lead is bent to function as a spring.

4. A resin-molded semiconductor device comprising:
a semiconductor chip having electrode pads;
a die pad for supporting the semiconductor chip thereon;
support leads for supporting the die pad;
signal-connecting leads;
connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and
a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members,
wherein respective lower parts of the die pad and the signal-connecting leads are at least partially not covered with the resin encapsulant but exposed, and
wherein each said support lead extends from an associated corner of the die pad to reach a side face of the resin encapsulant and is partially bent to function as a spring.

6. A resin-molded semiconductor device comprising:
a semiconductor chip having electrode pads;
a die pad for supporting the semiconductor chip thereon;
support leads for supporting the die pad;
signal-connecting leads;
connecting members for electrically connecting the electrode pads of the semiconductor chip to the signal-connecting leads; and
a resin encapsulant for encapsulating the die pad, the semiconductor chip, the signal-connecting leads and the connecting members,
wherein respective lower parts of the die pad and the signal-connecting leads are at least partially not covered with the resin encapsulant but exposed, the support leads are provided between the die pad and the signal-connecting leads, and each said support lead is partially bent to function as a spring.

UP 2000-08

1 / 1 LGST - Legal Status -
©EPO

US6081029 19990204 US/ASA [NMC]ASSIGNMENTOWNER: MATSUSHITA ELECTRONICS CORPORATION, J...

PN US6081029 A 20000627 [US6081029](A) Patent

AP US24407499 19990204 [1999US-0244074]
19990204 US-API [POS; EXM]
FILING DETAILS

PUB US24407499 19990204 [1999US-0244074]
20000627 US-A [POS; EXM]
Patent
US6081029 A 20000627 [US6081029]

ACT 19990204 US/AS-A [NMC]
ASSIGNMENT

OWNER: MATSUSHITA ELECTRONICS CORPORATION, JAPAN; EFFECTIVE DATE: 19990129
ASSIGNMENT OF ASSIGNORS INTEREST;ASSIGNOR:YAMAGUCHI, YUKIO;REEL/FRAME:009753/0250

20020129 US/AS-A [NMC]
ASSIGNMENT
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION /AR;REEL/FRAME:012495/0898

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OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

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ASSIGNMENT
OWNER: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., JAPAN; EFFECTIVE DATE: 20010404
CHANGE OF NAME;ASSIGNOR:MATSUSHITA ELECTRONICS CORPORATION;REEL/FRAME:012495/0898

LEG NMC
Alive
UP 2009-18

1 / 1 CRXX - US Claims Reassignations -
©CLAIMS/RRX

US6081029 20020129 REASSIGNEDCHANGE OF NAMEAssignor: MATSUSHITA ELECTRONICS CORPORATIO...
AN 3343780
PN 6,081,029 A 20000627 [US6081029]
PA Matsushita Electronics Corp JP
PT E (Electrical)
20020129 REASSIGNED
CHANGE OF NAME

Assignor: MATSUSHITA ELECTRONICS CORPORATION DATE SIGNED: 04/04/2001

ACT Assignee: MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMA KADOMA CITY, OSAKA JAPAN

Reel 012495/Frame 0898

Contact: SUGHRUE MION, PLLC DAVID J. CUSHING 2100 PENNSYLVANIA AVENUE, N.W. SUITE 800 WASHINGTON, D.C. 20037-3213

UP 2002-28
URAS 2002-07-09

Search statement 2

Patent Search 6081029 7/20/2009

No cases found.

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(Charges for search still apply)

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Source: **Combined Source Set 10 - Utility, Design and Plant Patents**
Terms: **Patno=6081029** (Edit Search | Suggest Terms for My Search)

244074 (09) 6081029 June 27, 2000

UNITED STATES PATENT AND TRADEMARK OFFICE GRANTED PATENT

6081029

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June 27, 2000

Resin encapsulated semiconductor device having a reduced thickness and improved reliability

INVENTOR: Yamaguchi, Yukio - Shiga, Japan (JP)

APPL-NO: 244074 (09)

FILED-DATE: February 4, 1999

GRANTED-DATE: June 27, 2000

PRIORITY: March 12, 1998 - 10060811, Japan (JP)

ASSIGNEE-PRE-ISSUE: February 4, 1999 - ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS)., MATSUSHITA ELECTRONICS CORPORATION 1-1, SAIWAI-CHO, TAKATSUKI-SHIOSAKA 59-1193, (1), Reel and Frame Number: 009753/0250

ASSIGNEE-AT-ISSUE: Matsushita Electronics Corporation, Osaka, Japan (JP), Foreign company or corporation (03)

ASSIGNEE-AFTER-ISSUE: January 29, 2002 - CHANGE OF NAME (SEE DOCUMENT FOR DETAILS)., MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD. NO. 1006 KADOMAKADOMA CITY, OSAKA, (1), Reel and Frame Number: 012495/0898

LEGAL-REP: McDermott, Will & Emery

PUB-TYPE: June 27, 2000 - Utility Patent having no previously published pre-grant publication (A)

PUB-COUNTRY: United States (US)

US-MAIN-CL: 257#718

US-ADDL-CL: 257#666, 257#675, 257#684, 257#692, 257#696, 257#698, 257#797, 257#E23.045, 257#E23.046, 257#E23.047, 257#E23.125

CL: 257

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pre/N	precedes by N words	and not	and not

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Suggestions:

- Check for spelling errors .
- Remove some search terms.
- Use more common search terms, such as those listed in "Suggested Words and Concepts"
- Use a less restrictive date range.

Save this Search as an Alert | Edit Search

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Suggest terms for my search

Check spelling

Search

Restrict by Document Segment

Select a document segment, enter search terms for the segment, then click Add.

Select a Segment | Add

Note: Segment availability differs between sources. Segments may not be applied consistently across sources.

Restrict by Date

No Date Restrictions | From | To | Date formats...

Search Connectors

and	and	w/p	in same paragraph
or	or	w/seg	in same segment
w/N	within N words	w/s	in same sentence
pre/N	precedes by N words	and not	and not

> More Connectors & Commands...

How Do I...?

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> Use wildcards as placeholders for one or more characters in a search term?

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2. Business Wire, October 16, 1995, Monday, 1299 words, Brio Industries reports sharply improved results for second quarter and six months, VANCOUVER, British Columbia ... income taxes 1,103,916 **(6,081,029)** Income (taxes) recovery (...

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